

74HC11-Q100; 74HCT11-Q100

Triple 3-input AND gate

Rev. 2 — 22 March 2013

Product data sheet

1. General description

The 74HC11-Q100; 74HCT11-Q100 is a triple 3-input AND gate. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD7A
- Input levels:
 - ◆ For 74HC11-Q100: CMOS level
 - ◆ For 74HCT11-Q100: TTL level
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200\text{ pF}$, $R = 0\text{ }\Omega$)
- Multiple package options

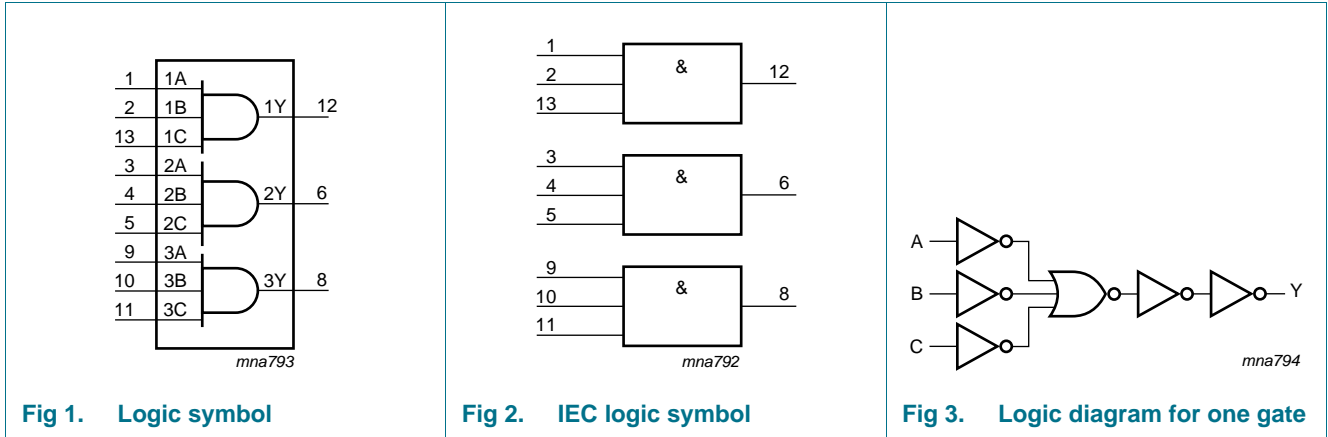
3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|---------------------------------|---|---------|---|----------|
| | Temperature range | Name | Description | Version |
| 74HC11D-Q100 74HCT11D-Q100 | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | SO14 | plastic small outline package; 14 leads; body width 3.9 mm | SOT108-1 |
| 74HC11PW-Q100 74HCT11PW-Q100 | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP14 | plastic thin shrink small outline package; 14 leads; body width 4.4 mm | SOT402-1 |

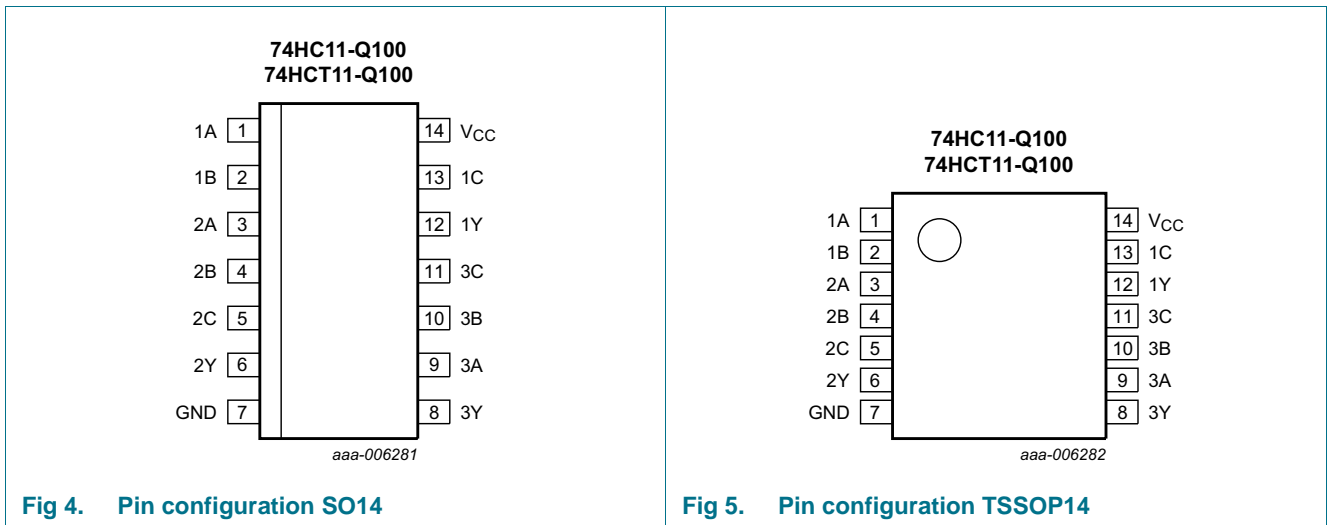


4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|-----------------|-----------|----------------|
| 1A, 2A, 3A | 1, 3, 9 | data input |
| 1B, 2B, 3B | 2, 4, 10 | data input |
| GND | 7 | ground (0 V) |
| 1C, 2C, 3C | 13, 5, 11 | data input |
| 1Y, 2Y, 3Y | 12, 6, 8 | data output |
| V _{CC} | 14 | supply voltage |

6. Functional description

Table 3. Function selection^[1]

| Input | | | Output |
|-------|----|----|--------|
| nA | nB | nC | nY |
| L | X | X | L |
| X | L | X | L |
| X | X | L | L |
| H | H | H | H |

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|--|-------|------|------|
| V_{CC} | supply voltage | | -0.5 | +7 | V |
| I_{IK} | input clamping current | $V_I < -0.5 \text{ V}$ or $V_I > V_{CC} + 0.5 \text{ V}$ | [1] - | ±20 | mA |
| I_{OK} | output clamping current | $V_O < -0.5 \text{ V}$ or $V_O > V_{CC} + 0.5 \text{ V}$ | [1] - | ±20 | mA |
| I_O | output current | $-0.5 \text{ V} < V_O < V_{CC} + 0.5 \text{ V}$ | - | ±25 | mA |
| I_{CC} | supply current | | - | 50 | mA |
| I_{GND} | ground current | | -50 | - | mA |
| T_{stg} | storage temperature | | -65 | +150 | °C |
| P_{tot} | total power dissipation | SO14 and TSSOP14 packages | [2] - | 500 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 package: P_{tot} derates linearly with 8 mW/K above 70 °C.
For TSSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

| Symbol | Parameter | Conditions | 74HC11-Q100 | | | 74HCT11-Q100 | | | Unit |
|------------------|-------------------------------------|-------------------------|-------------|------|-----------------|--------------|------|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 6.0 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| T _{amb} | ambient temperature | | -40 | - | +125 | -40 | - | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 2.0 V | - | - | 625 | - | - | - | ns/V |
| | | V _{CC} = 4.5 V | - | 1.67 | 139 | - | 1.67 | 139 | ns/V |
| | | V _{CC} = 6.0 V | - | - | 83 | - | - | - | ns/V |

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|--------------------|---------------------------|--|-------|------|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC11-Q100 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | 1.2 | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 4.5 V | 3.15 | 2.4 | - | 3.15 | - | 3.15 | - | V |
| | | V _{CC} = 6.0 V | 4.2 | 3.2 | - | 4.2 | - | 4.2 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | 0.8 | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 4.5 V | - | 2.1 | 1.35 | - | 1.35 | - | 1.35 | V |
| | | V _{CC} = 6.0 V | - | 2.8 | 1.8 | - | 1.8 | - | 1.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = -20 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -20 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -20 μA; V _{CC} = 6.0 V | 5.9 | 6.0 | - | 5.9 | - | 5.9 | - | V |
| | | I _O = -4.0 mA; V _{CC} = 4.5 V | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 20 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 6.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 4.5 V | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.1 | - | ±1 | - | ±1 | μA |
| | | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V | - | - | 2.0 | - | 20 | - | 40 | μA |

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|---------------------|---------------------------|---|-------|------|------|------------------|-----|-------------------|-----|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |
| 74HCT11-Q100 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2.0 | 1.6 | - | 2.0 | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 4.5 V to 5.5 V | - | 1.2 | 0.8 | - | 0.8 | - | 0.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = -20 µA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -4.0 mA | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 20 µA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 5.5 V | - | - | ±0.1 | - | ±1 | - | ±1 | µA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 2.0 | - | 20 | - | 40 | µA |
| ΔI _{CC} | additional supply current | per input pin; V _I = V _{CC} - 2.1 V; I _O = 0 A; other inputs at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V | - | 100 | 360 | - | 450 | - | 490 | µA |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |

10. Dynamic characteristics

Table 7. Dynamic characteristicsGND = 0 V; C_L = 50 pF; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | Unit |
|--------------------|-------------------------------|--|---------------------|---------------------|-----|-------------------|--------------|------|
| | | | Min | Typ | Max | Max (85 °C) | Max (125 °C) | |
| 74HC11-Q100 | | | | | | | | |
| t _{pd} | propagation delay | nA, nB to nY; see Figure 6 | | [1] | | | | |
| | | V _{CC} = 2.0 V | - | 32 | 100 | 125 | 150 | ns |
| | | V _{CC} = 4.5 V | - | 12 | 20 | 25 | 30 | ns |
| | | V _{CC} = 5.0 V; C _L = 15 pF | - | 9 | - | - | - | ns |
| t _t | transition time | see Figure 6 | | [2] | | | | |
| | | V _{CC} = 2.0 V | - | 19 | 75 | 95 | 110 | ns |
| | | V _{CC} = 4.5 V | - | 7 | 15 | 19 | 22 | ns |
| | | V _{CC} = 6.0 V | - | 6 | 13 | 16 | 19 | ns |
| C _{PD} | power dissipation capacitance | per package; V _I = GND to V _{CC} | [3] | - | 18 | - | - | pF |

Table 7. Dynamic characteristics
 GND = 0 V; $C_L = 50$ pF; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | Unit | |
|---------------------|-------------------------------|--|-------|-----|-----|-------------------|--------------|------|----|
| | | | Min | Typ | Max | Max (85 °C) | Max (125 °C) | | |
| 74HCT11-Q100 | | | | | | | | | |
| t_{pd} | propagation delay | nA, nB to nY; see Figure 6 | [1] | | | | | | |
| | | $V_{CC} = 4.5$ V | - | 16 | 24 | 30 | 36 | ns | |
| | | $V_{CC} = 5.0$ V; $C_L = 15$ pF | - | 11 | - | - | - | ns | |
| t_t | transition time | $V_{CC} = 4.5$ V; see Figure 6 | [2] | - | 7 | 15 | 19 | 22 | ns |
| C_{PD} | power dissipation capacitance | per package; $V_I = \text{GND to } V_{CC} - 1.5$ V | [3] | - | 20 | - | - | - | pF |

- [1] t_{pd} is the same as t_{PHL} and t_{PLH} .
- [2] t_t is the same as t_{THL} and t_{TLH} .
- [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms

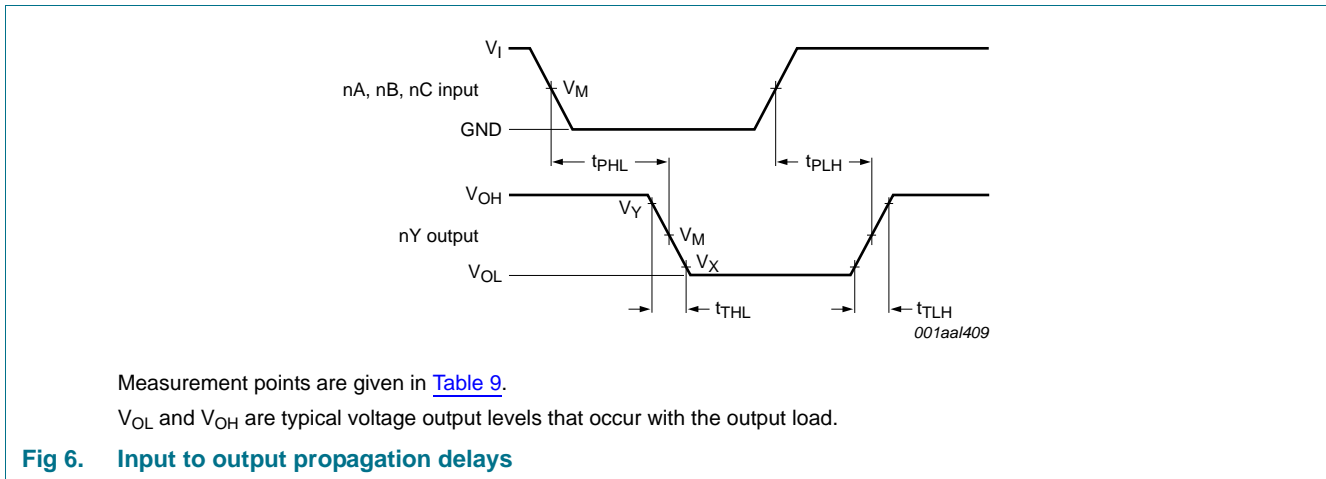
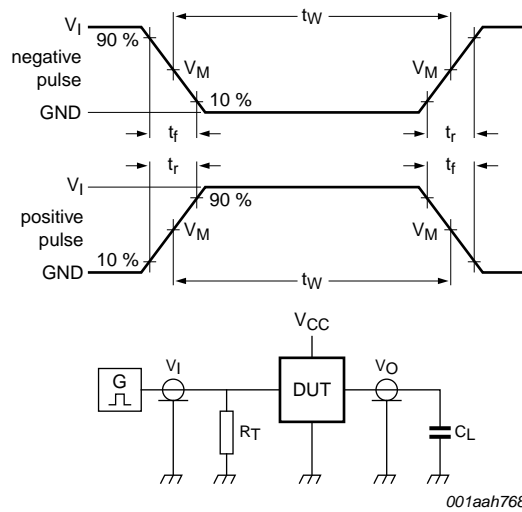


Table 8. Measurement points

| Type | Input | Output | | |
|--------------|-------------|-------------|-------------|-------------|
| | V_M | V_M | V_X | V_Y |
| 74HC11-Q100 | $0.5V_{CC}$ | $0.5V_{CC}$ | $0.1V_{CC}$ | $0.9V_{CC}$ |
| 74HCT11-Q100 | 1.3 V | 1.3 V | $0.1V_{CC}$ | $0.9V_{CC}$ |



001aah768

Test data is given in [Table 9](#).

Definitions test circuit:

R_T = termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = load capacitance including jig and probe capacitance.

Fig 7. Test circuit for measuring switching times

Table 9. Test data

| Type | Input | | Load | Test |
|--------------|----------|------------|--------------|--------------------|
| | V_I | t_r, t_f | C_L | |
| 74HC11-Q100 | V_{CC} | 6.0 ns | 15 pF, 50 pF | t_{PLH}, t_{PHL} |
| 74HCT11-Q100 | 3.0 V | 6.0 ns | 15 pF, 50 pF | t_{PLH}, t_{PHL} |

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

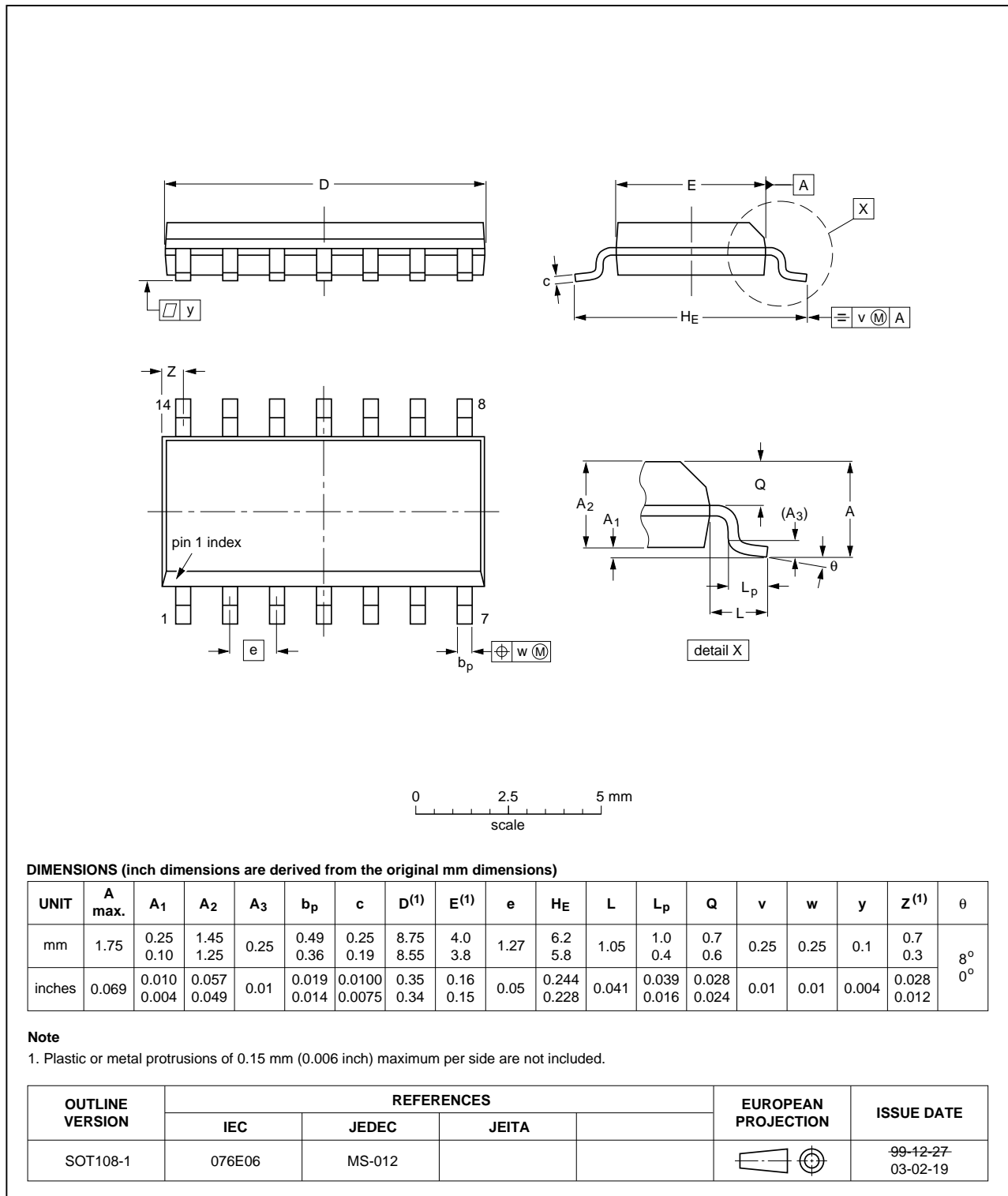


Fig 8. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

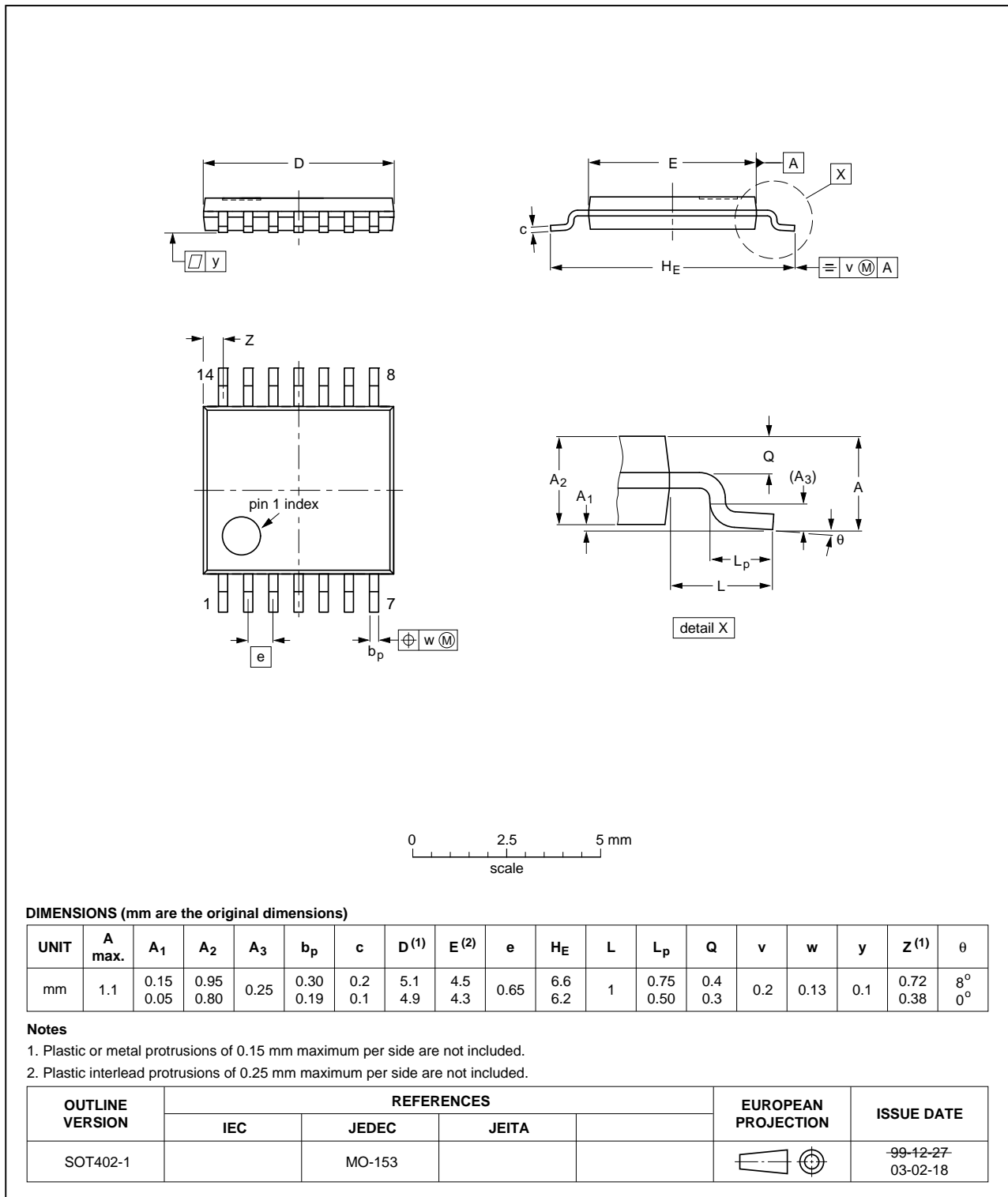


Fig 9. Package outline SOT402-1 (TSSOP14)

13. Abbreviations

Table 10. Abbreviations

| Acronym | Description |
|---------|--|
| CMOS | Complementary Metal-Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| LSTTL | Low-power Schottky Transistor-Transistor Logic |
| MM | Machine Model |
| MIL | Military |
| TTL | Transistor-Transistor Logic |

14. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------|---|--------------------|---------------|---------------------|
| 74HC_HCT11_Q100 v.2 | 20130322 | Product data sheet | - | 74HC_HCT11_Q100 v.1 |
| Modifications: | • Section 2 "Features and benefits" removed redundant temperature range | | | |
| 74HC_HCT11_Q100 v.1 | 20130228 | Product data sheet | - | - |

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15.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
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